

Intel® LXT16642/LXT16653 Serializer/Deserializer Chipset

Product Description

The Intel® LXT16642 and the Intel® LXT16653 form a high-performance Serializer/Deserializer (SerDes) chipset for use in DWDM applications, SDH STM 16/4, and SONET OC-48/12 Optical telecommunications systems, and Backplane applications. The chipset meets the ITU-T and Telcordia recommendations.

The Intel® LXT16642/53 chipset is manufactured in a well-proven silicon bipolar technology that offers the performance, stability, and reliability customers require for optical communication systems.

The devices are operated from a single power supply from +2.9V to 3.6V. Power dissipation is typically 370mW for the LXT16642 and 450mW for the LXT16653.

The LXT16642 is a high-performance integrated multi-bit rate Clock and Data Recovery device (CDR) with 1:4 Demultiplexer (DeMUX), digital phase detector, out of lock



monitor, Phase Locked Loop (PLL) control circuit, and Limiting Amplifier (LIA). The system interface is 4-bit LVDS.

The LXT16653 is a high-performance integrated multi-bit rate transmitter featuring a 4:1 Multiplexer (MUX) with integrated clock generation and PLL circuits. The fully integrated on-chip PLLs eliminate critical clock and data timing relations and feature the unique dynamic phase alignment between ASIC and MUX. The continuous handling of "round trip delay variations" by the source synchronous clocking ensures easy external optimization of jitter. The system interface is 4-bit LVDS.

LXT16642 DeMUX

Features

- Single power supply: +2.9V to +3.6V
- Power dissipation: 370mW
- Interfaces to IXF6192
- 4x LXT16642 interfaces to IXF6192
- Typically 2x 1.8mVpp @ PRBS 2²³-1, BER <10⁻¹²
- 32-pin QFN

Benefits

- Easy board design and integration
- High integration
- Aggregation point between OC-48 and OC-192
- Increased performance
- Small physical form factor (5mm x 5mm)
- Reduced board space

LXT16653 MUX

Features

- Single power supply: +2.9V to +3.6V
- Power dissipation: 450mW
- Interfaces to IXF6192
- 4x LXT16653 interfaces to IXF6192
- Dynamic Phase Alignment based on PLL
- 48-pin QFN

Benefits

- Easy board design and integration
- High integration
- Aggregation point between OC-48 and OC-192
- Infinite phase margin tolerance
- Small physical form factor (7mm x 7mm)
- Reduced board space

Key Features

- Low-power, small physical form, and high integration make the chipset ideal for Module and Backplane applications
- Easy external optimization of jitter is enabled by a Dynamic Phase Alignment based on PLL
- External reference clock facilitates fast acquisition

Key Applications

- SDH STM 16/4
- SONET OC-48/12
- Backplane
- Aggregation points between OC-48 and OC-192
- DWDM low-power/low-form factor applications

Application Overview

Intel provides reliable high-performance receivers and transmitters for optical line cards.

Receiver Line Card

An optical reception system receives an optical signal and converts it into an electrical signal. The optical receiver, which can be a PIN diode or an Avalanche Photo Detector (APD), converts the optical input to a small electrical current. A Transimpedance Amplifier (TIA), also known as a post-amplifier, then converts the current to an electrical voltage. The TIA signal, which varies from a few mV up to 50mVpp or more, can be

passed to an AGC amplifier or a LIA. This produces a signal of sufficient amplitude/power to drive the next building block (see Figure 1).

A CDR converts the analog input signal to a digital bit stream with an associated clock, and the serial high-speed data stream is finally converted to a parallel signal at lower speed. This signal then interfaces to the digital processing system.

The key function block in the CDR is the PLL, which locks onto the incoming data stream. The phase detector is equipped with a discriminator that evaluates the incoming data signal in the middle of the bit period (the “eye”) and determines whether a 1 or a 0 is received.

A separate Lock Detector determines whether the incoming data rate deviates too much from a given frequency. If data input is absent or deviates too much, the external reference clock ensures that the VCO remains in a selectable ± 500 to $\pm 2,000$ ppm capture range.

Phase noise and amplitude noise, also known as jitter, can cause incorrect determination of data bits (bit errors) in the input signal. When a valid input signal is applied both differential data and clock outputs are provided.

The DeMUX transforms the serial data signals into four parallel data signals at a corresponding lower data rate. If, for example, a 2.488Gbps signal (OC-48/STM 16) is fed into a 1:4 DeMUX, it will produce four parallel data outputs at 622.08Mbps.

Clock output from the CDR is used to clock the data on the parallel interface into the next device. The Intel LXT16642 has a DeMUX merged together with a CDR and is fully compliant with the Optical Interface Forum's SFI recommendation on common electrical interface between framers and SerDes.

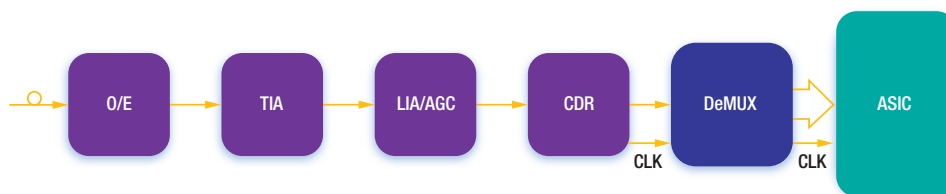


Figure 1. Typical receiver line card

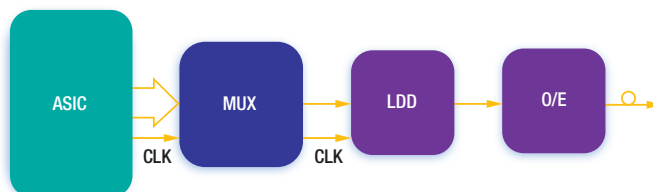


Figure 2. Typical transmitter line card

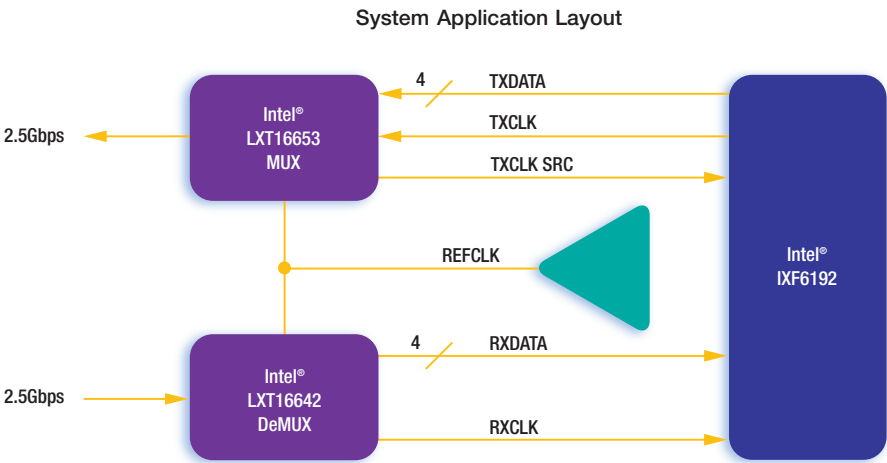
Transmitter Line Card

In the optical transmission system, the parallel signal from the processing system is converted to a serial signal of the bit rate of the optical link. The serial signal is amplified before it is fed to the laser, which converts the signal to an electrical signal. The quality of the transmitted optical signal (and so the maximum transmission distance) is highly dependent on the jitter of the serial bit stream. The jitter is the phase noise most commonly caused by the uncertainty or variations in the bit periods. To resolve this, Intel has directed significant effort in the system and component design at maintaining precise, constant duration of the bit periods in the outgoing data stream (see Figure 2).

The MUX has the opposite functions of the DeMUX. For example, the MUX might convert a 4-bit parallel signal

into one serial bit stream at a corresponding higher data rate. When four parallel inputs at 622.08Mbps are fed into a 4:1 MUX, the output data rate will be 2.488Gbps for OC-48/STM 16.

The clock interconnections between the MUX and the data source (such as the framer) can be complex in high-speed applications. In high-speed clock operation for MUXs, the input sampling clock must be in the phase to ensure correct loading of the data into the MUX so that input data can be sampled correctly. In addition, the internal high-speed clock used for shifting data to the laser must be as clean as possible to minimize the jitter in the output signal. Two PLLs are implemented in each MUX to accommodate these critical requirements.



Support Collateral/Tools

Item	Description	Order Number
Application Brief	■ Intel® IXD66014 10Gbps Line Card Solution for FEC Enabled SONET/SDH Optical Networking Applications Utilizing Intel® IXF32003, GD16588/GD16589**, LXT16642/LXT16653, and GD16590** products in the Intel® IXD66014 Line Card Reference Design	250219

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UNITED STATES AND CANADA
Intel Corporation
Robert Noyce Building
2200 Mission College Blvd.
P.O. Box 58119
Santa Clara, CA 95052-8119
USA

EUROPE
Intel Corporation (UK) Ltd.
Pipers Way
Swindon
Wiltshire SN3 1RJ
UK

ASIA-PACIFIC
Intel Semiconductor Ltd.
32/F Two Pacific Place
88 Queensway, Central
Hong Kong, SAR

JAPAN
Intel Japan (Tsukuba HQ)
5-6
Tokodai Tsukuba-shi
300-2635 Ibaraki-ken
Japan

SOUTH AMERICA
Intel Semicondutores do Brasil LTDA
Av. Dr. Chucuri Zaidan, 940-10° andar
04583-904 São Paulo, SP
Brazil